

FIG. 1

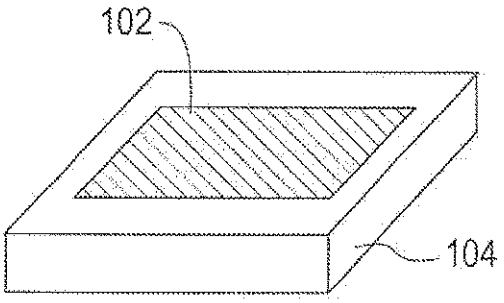


FIG. 2

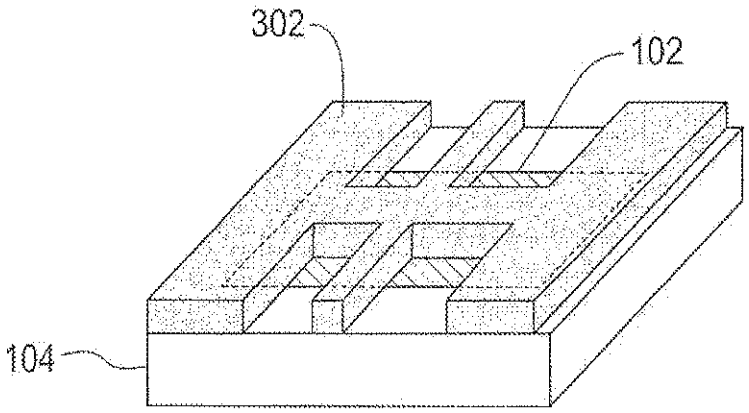


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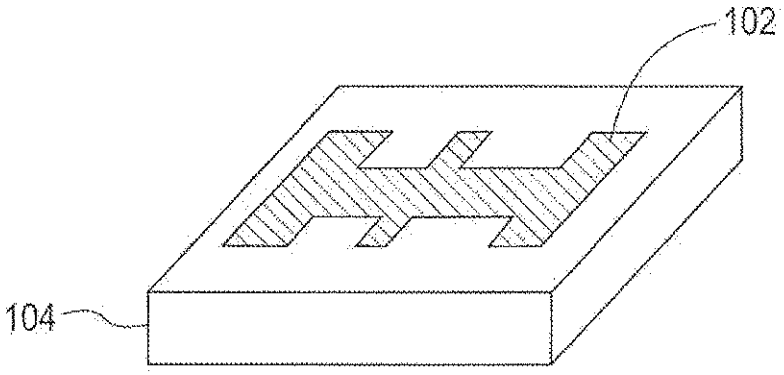


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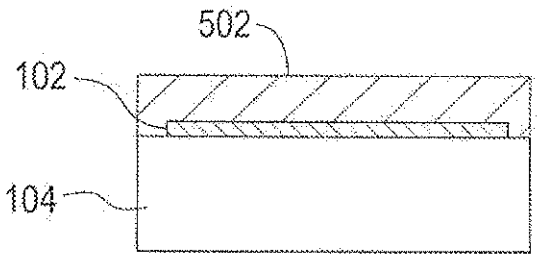


FIG. 5

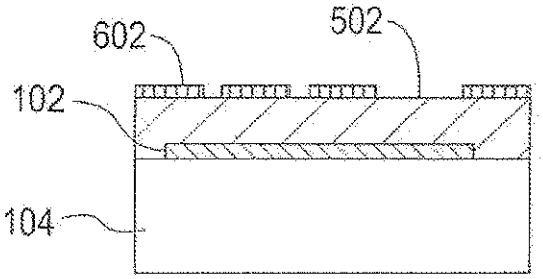


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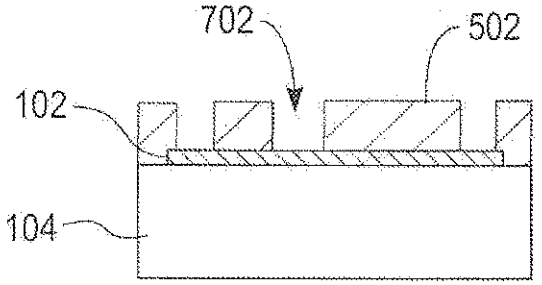


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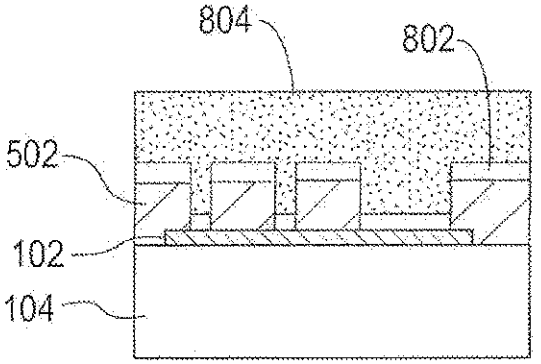


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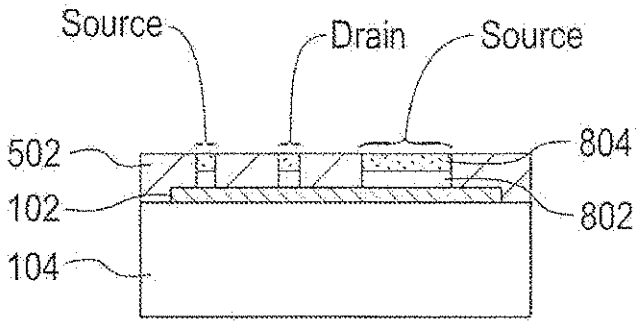


FIG. 9

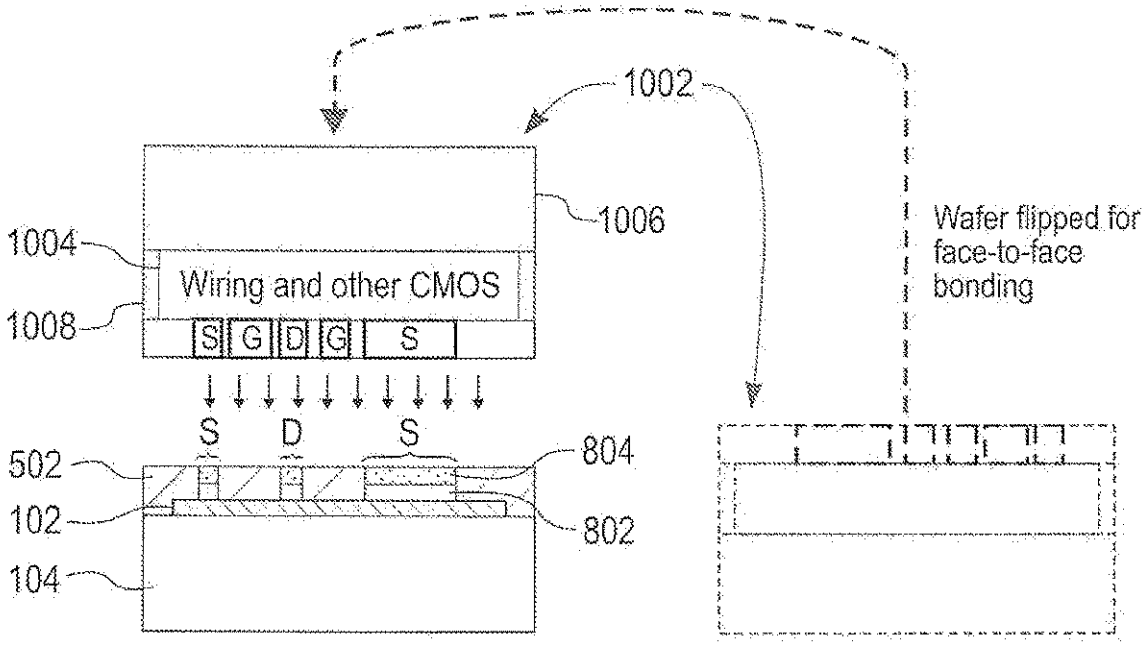

1002
1006
1004
Wiring and other CMOS
1008
S G D G S
Wafer flipped for face-to-face bonding
S D S
502
804
102
802
104

FIG. 10

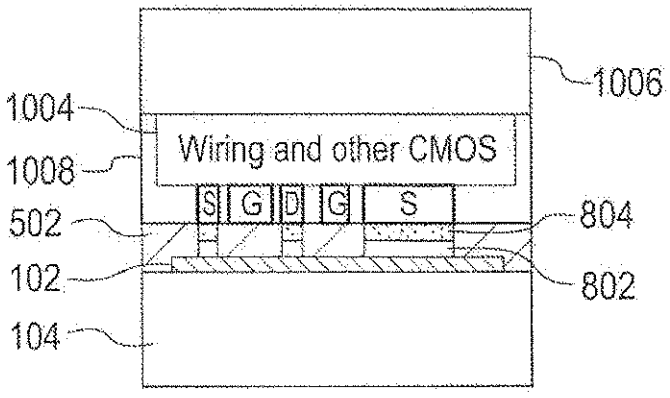

1006
1004
Wiring and other CMOS
1008
S G D G S
502
804
102
802
104

FIG. 11

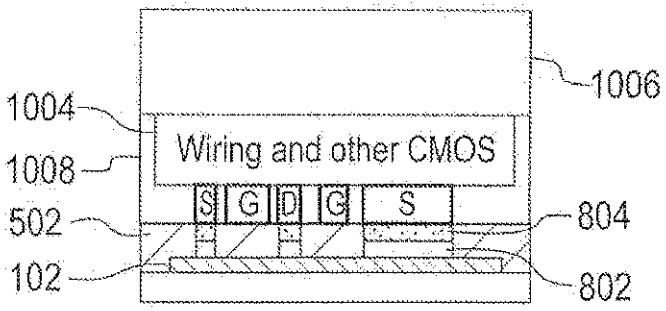


FIG. 12

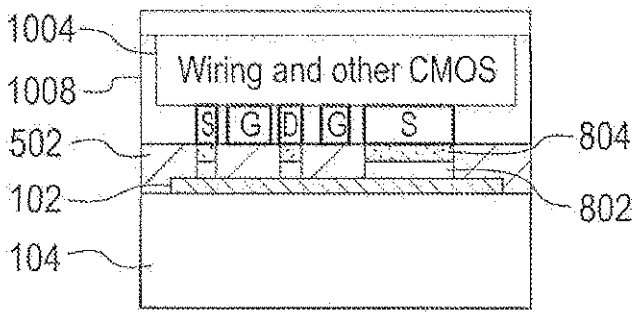


FIG. 13

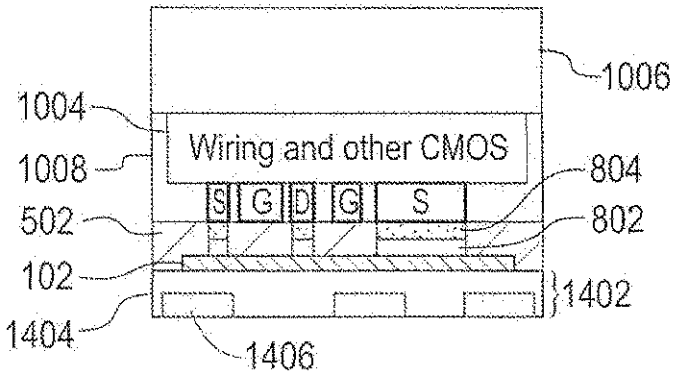


FIG. 14

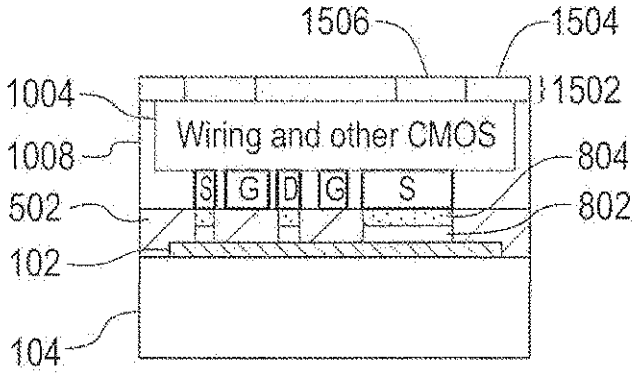


FIG. 15

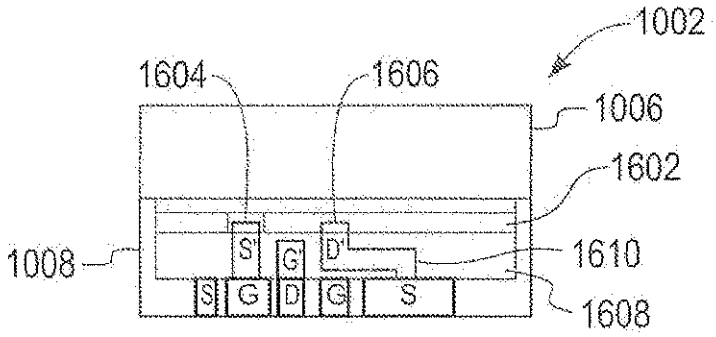


FIG. 16

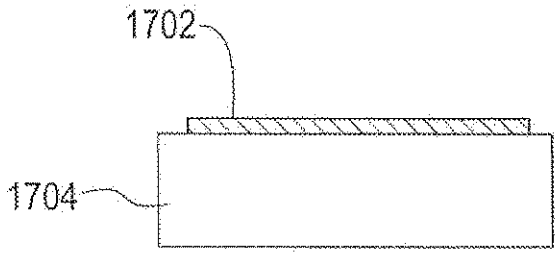


FIG. 17

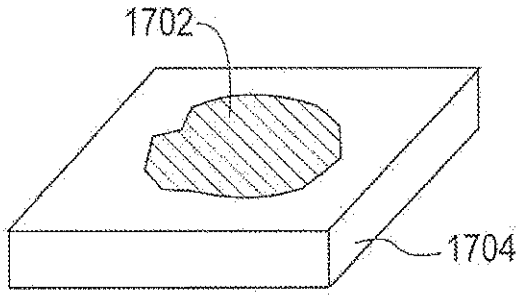


FIG. 18

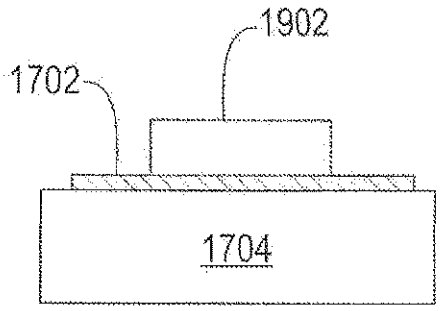


FIG. 19

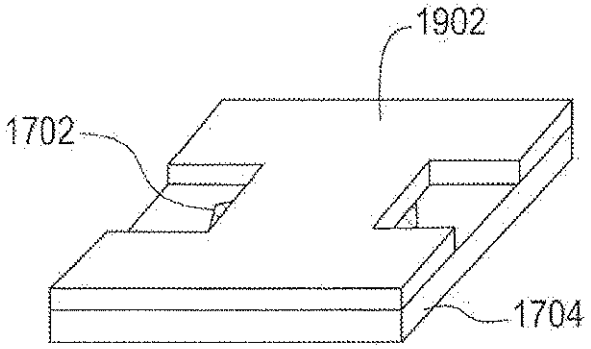


FIG. 20

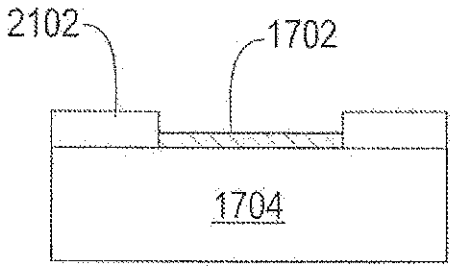


FIG. 21

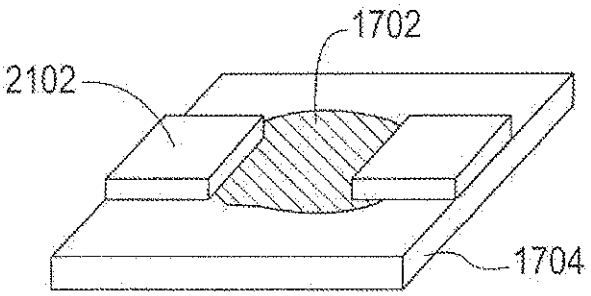


FIG. 22

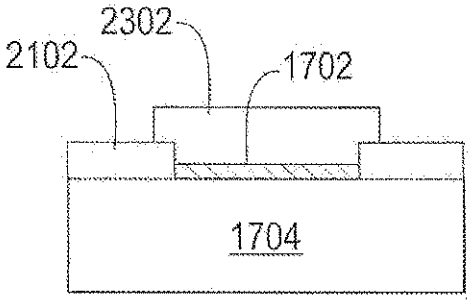


FIG. 23

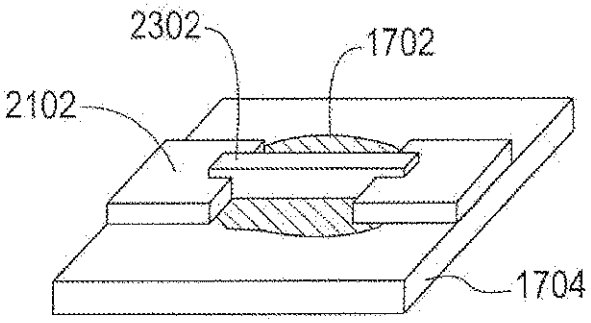


FIG. 24

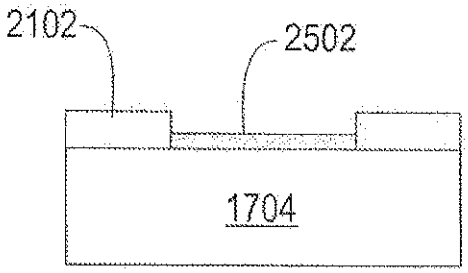


FIG. 25

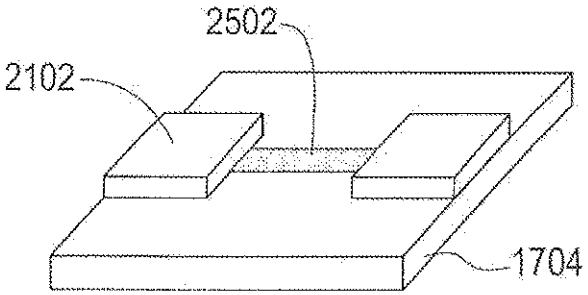


FIG. 26

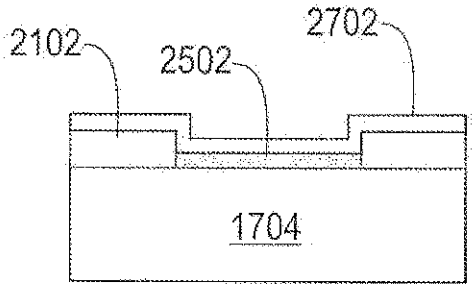


FIG. 27

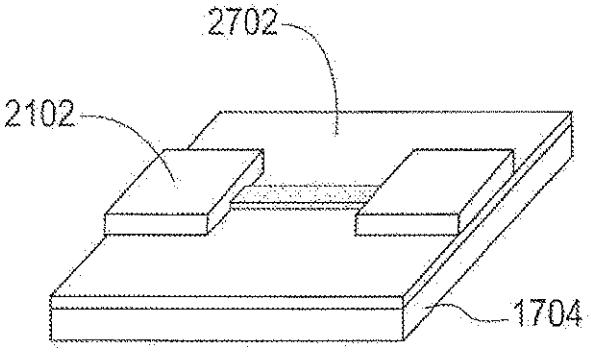


FIG. 28

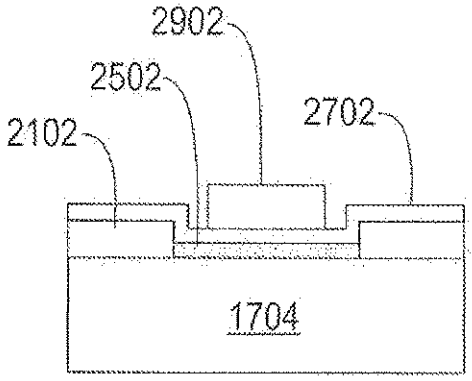


FIG. 29

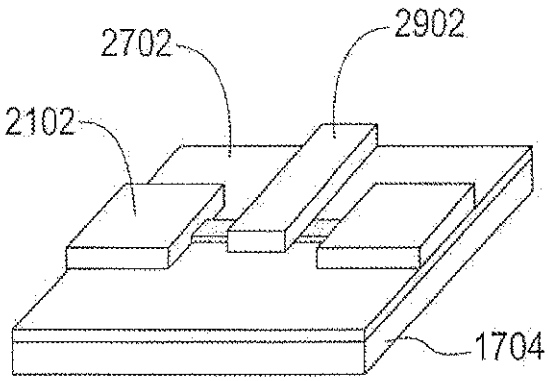


FIG. 30

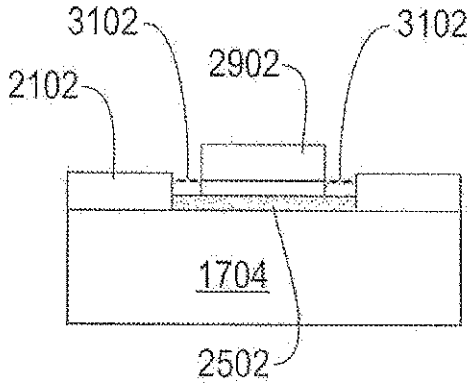


FIG. 31

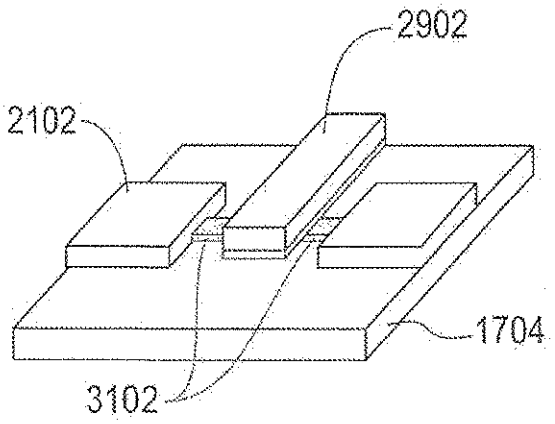


FIG. 32

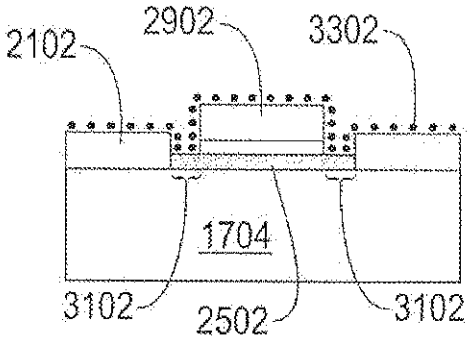


FIG. 33

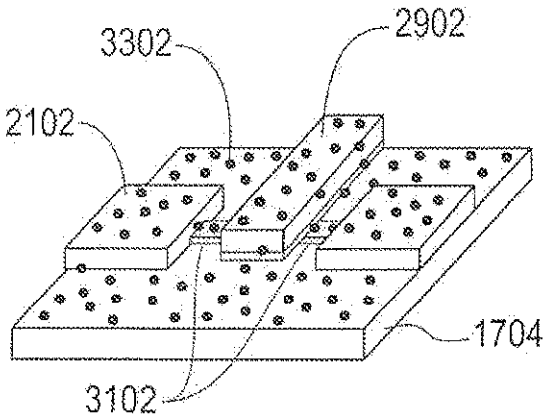


FIG. 34

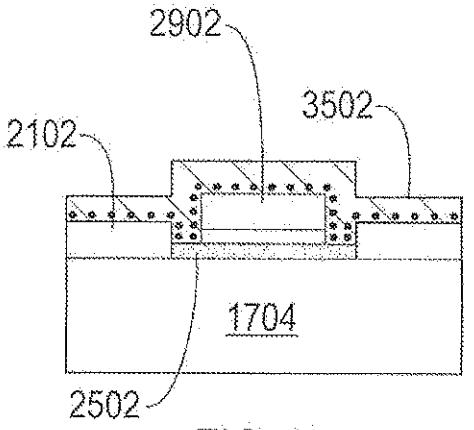


FIG. 35

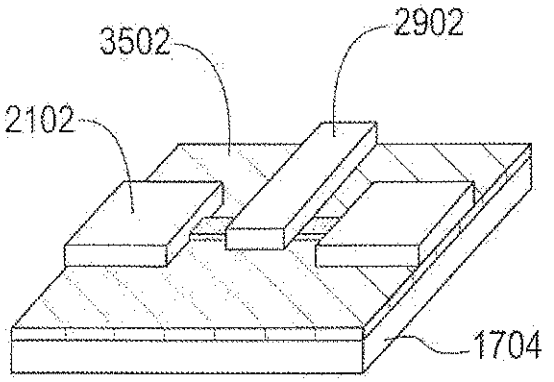


FIG. 36